



Save the Date!

11th IEEE Electronics System-Integration Technology Conference
Helsinki, Finland | 9-11 September 2026

The IEEE Electronics System-Integration Technology Conference (IEEE ESTC 2026) is the premier international event in the field of electronics packaging and system integration. The conference is held biennially in Europe. It is sponsored by IEEE-EPS and co-sponsored by IMAPS Europe. The 2026 edition will take place from 9 to 11 September in Helsinki, Finland, and will focus on microelectronics and system integration, including their application in industry.

You are invited to submit an abstract of max. 600 words (and two optional figures) via the [online submission portal](#) by March 1, 2026. This exciting conference will cover the following topics:

- **Advanced Packaging**
- **Materials for Interconnects and Packaging**
- **Optoelectronic Systems Packaging**
- **Assembly and Manufacturing Technologies**
- **Design Tools and Modeling**
- **Power Electronics System Packaging**
- **Advanced Technologies for Emerging Systems**
- **Reliability of Electronic Devices and Systems**
- **Flexible, Printed and Hybrid Electronics**
- **RF, mm-wave and THz Systems Packaging**

In addition to the technical program, IEEE ESTC will also feature Professional Development Courses and an exhibition showcasing the latest products, technologies, and solutions from industry leaders. More details can be found on the [conference website](#).

We look forward to welcoming you to IEEE ESTC 2026 in Helsinki!